

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

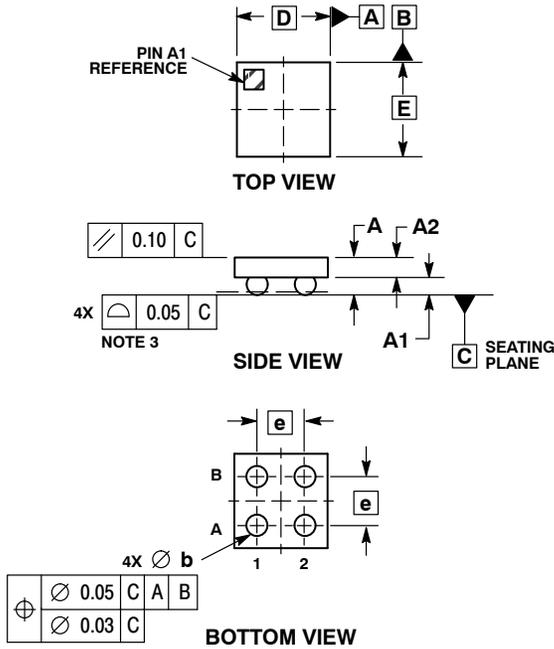
ON Semiconductor®



SCALE 4:1

4 PIN FLIP-CHIP, 1.6x1.6
CASE 499BB
ISSUE A

DATE 14 JAN 2009

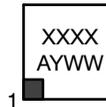


NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.64
A1	0.22	0.28
A2	0.34	0.36
b	0.29	0.34
D	1.52	1.60
E	1.52	1.60
e	0.80 BSC	

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	4 PIN FLIP-CHIP, 1.6X1.6, 0.8P	PAGE 1 OF 2

